



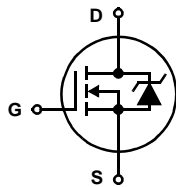
**THE DATASHEET OF  
HUF76013P3**



**20A, 20V, 0.022 Ohm, N-Channel, Logic Level Power MOSFETs**

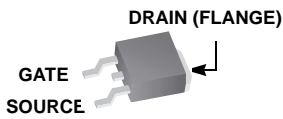
The HUF76013 is an application-specific MOSFET optimized for switching when used as the upper switch in synchronous buck applications. The low gate charge and low input capacitance results in lower driver and lower switching losses thereby increasing the overall system efficiency.

**Symbol**

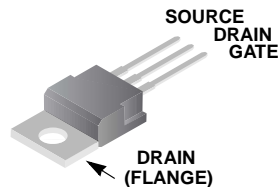


**Packaging**

HUF76013D3S  
JEDEC TO-252AA



HUF76013P3  
JEDEC TO-220AB



**Features**

- 20A, 20V
  - $r_{DS(ON)} = 0.022\Omega$ ,  $V_{GS} = 10V$
  - $r_{DS(ON)} = 0.030\Omega$ ,  $V_{GS} = 5V$
- PWM Optimized for Synchronous Buck Applications
- Fast Switching
- Low Gate Charge
  - $Q_g$  Total 14nC (Typ)
- Low Capacitance
  - $C_{ISS}$  624pF (Typ)
  - $C_{RSS}$  71pF (Typ)

**Ordering Information**

PART NUMBER	PACKAGE	BRAND
HUF76013P3	TO-220AB	76013P
HUF76013D3S	TO-252AA	76013D

NOTE: When ordering, use the entire part number. Add the suffix T to obtain the HUF76013D3S in tape and reel, e.g., HUF76013D3ST.

**Absolute Maximum Ratings**  $T_C = 25^\circ C$ , Unless Otherwise Specified

SYMBOL	PARAMETER	HUF76013P3, HUF76013D3S	UNITS
$V_{DSS}$	Drain to Source Voltage (Note 1)	20	V
$V_{DGR}$	Drain to Gate Voltage ( $R_{GS} = 20k\Omega$ ) (Note 1)	20	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current		
$I_D$	Continuous ( $T_C = 25^\circ C$ , $V_{GS} = 10V$ ) (Figure 2)	20	A
$I_D$	Continuous ( $T_C = 100^\circ C$ , $V_{GS} = 5V$ )	20	A
$I_{DM}$	Pulsed Drain Current	Figure 4	A
$P_D$	Power Dissipation	50	W
	Derate Above $25^\circ C$	0.4	W/ $^\circ C$
$T_J, T_{STG}$	Operating and Storage Temperature	-55 to 150	$^\circ C$
$T_L$	Maximum Temperature for Soldering		$^\circ C$
$T_{pkg}$	Leads at 0.063in (1.6mm) from Case for 10s	300	$^\circ C$
	Package Body for 10s, See Techbrief TB334	260	$^\circ C$
<b>THERMAL SPECIFICATIONS</b>			
$R_{\theta JC}$	Thermal Resistance Junction to Case, TO-220, TO-252	2.5	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-220	62	$^\circ C/W$
	Thermal Resistance Junction to Ambient TO-252	100	$^\circ C/W$

NOTE:

1.  $T_J = 25^\circ C$  to  $125^\circ C$ .

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

## HUF76013P3, HUF76013D3S

### Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
<b>OFF STATE SPECIFICATIONS</b>							
Drain to Source Breakdown Voltage	$BV_{DSS}$	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$ (Figure 11)	20	-	-	V	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20\text{V}$ , $V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$	
		$V_{DS} = 20\text{V}$ , $V_{GS} = 0\text{V}$ , $T_C = 150^\circ\text{C}$	-	-	250	$\mu\text{A}$	
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA	
<b>ON STATE SPECIFICATIONS</b>							
Gate to Source Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$ (Figure 10)	1	-	3	V	
Drain to Source ON Resistance	$r_{DS(ON)}$	$I_D = 20\text{A}$ , $V_{GS} = 10\text{V}$ (Figures 8, 9)	-	0.018	0.022	$\Omega$	
		$I_D = 20\text{A}$ , $V_{GS} = 5\text{V}$ (Figure 8)	-	0.025	0.030	$\Omega$	
<b>SWITCHING SPECIFICATIONS (<math>V_{GS} = 5\text{V}</math>)</b>							
Turn-On Time	$t_{ON}$	$V_{DD} = 10\text{V}$ , $I_D = 20\text{A}$ $V_{GS} = 5\text{V}$ , $R_{GS} = 19\Omega$ (Figures 14, 18, 19)	-	-	197	ns	
Turn-On Delay Time	$t_{d(ON)}$		-	11	-	ns	
Rise Time	$t_r$		-	120	-	ns	
Turn-Off Delay Time	$t_{d(OFF)}$		-	19	-	ns	
Fall Time	$t_f$		-	30	-	ns	
Turn-Off Time	$t_{OFF}$		-	-	72	ns	
<b>SWITCHING SPECIFICATIONS (<math>V_{GS} = 10\text{V}</math>)</b>							
Turn-On Time	$t_{ON}$	$V_{DD} = 10\text{V}$ , $I_D = 20\text{A}$ $V_{GS} = 10\text{V}$ , $R_{GS} = 19\Omega$ (Figures 15, 18, 19)	-	-	151	ns	
Turn-On Delay Time	$t_{d(ON)}$		-	7	-	ns	
Rise Time	$t_r$		-	93	-	ns	
Turn-Off Delay Time	$t_{d(OFF)}$		-	37	-	ns	
Fall Time	$t_f$		-	29	-	ns	
Turn-Off Time	$t_{OFF}$		-	-	100	ns	
<b>GATE CHARGE SPECIFICATIONS</b>							
Total Gate Charge at 10V	$Q_{g(TOT)}$	$V_{GS} = 0\text{V}$ to 10V	$V_{DD} = 10\text{V}$ , $I_D = 20\text{A}$ , $I_{g(REF)} = 1.0\text{mA}$ (Figures 13, 16, 17)	-	14.4	17	nC
Total Gate Charge at 5V	$Q_{g(TOT)}$	$V_{GS} = 0\text{V}$ to 5V		-	7.8	9	nC
Threshold Gate Charge	$Q_{g(TH)}$	$V_{GS} = 0\text{V}$ to 1V		-	0.9	1	nC
Gate to Source Gate Charge	$Q_{gs}$			-	3.5	-	nC
Gate to Drain "Miller" Charge	$Q_{gd}$			-	3.2	-	nC
<b>CAPACITANCE SPECIFICATIONS</b>							
Input Capacitance	$C_{ISS}$	$V_{DS} = 20\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$ (Figure 12)	-	624	-	pF	
Output Capacitance	$C_{OSS}$		-	444	-	pF	
Reverse Transfer Capacitance	$C_{RSS}$		-	71	-	pF	

### Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	$V_{SD}$	$I_{SD} = 20\text{A}$	-	-	1.25	V
		$I_{SD} = 10\text{A}$	-	-	1.0	V
Reverse Recovery Time	$t_{rr}$	$I_{SD} = 20\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	55	ns
Reverse Recovered Charge	$Q_{RR}$	$I_{SD} = 20\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	82	nC

Typical Performance Curves

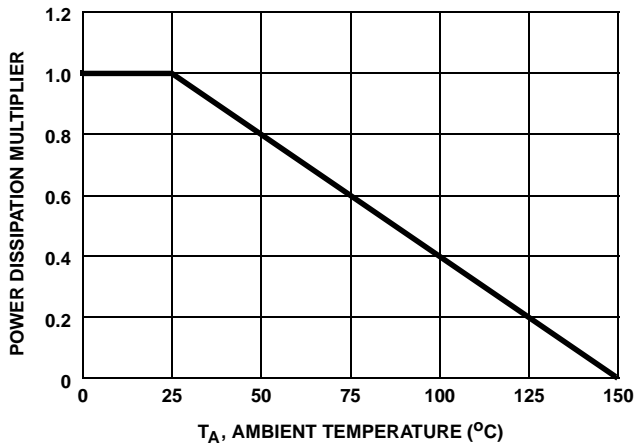


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

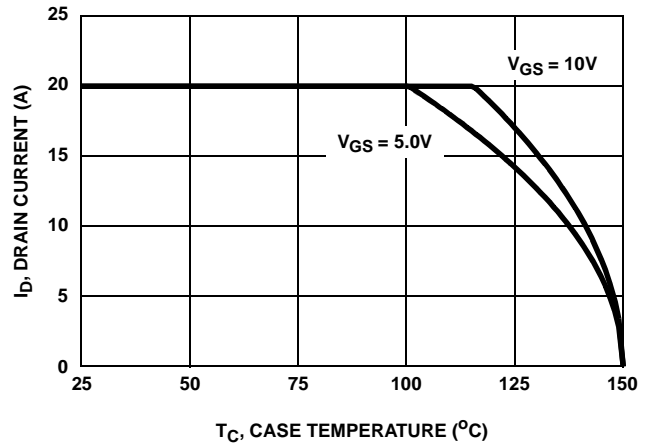


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

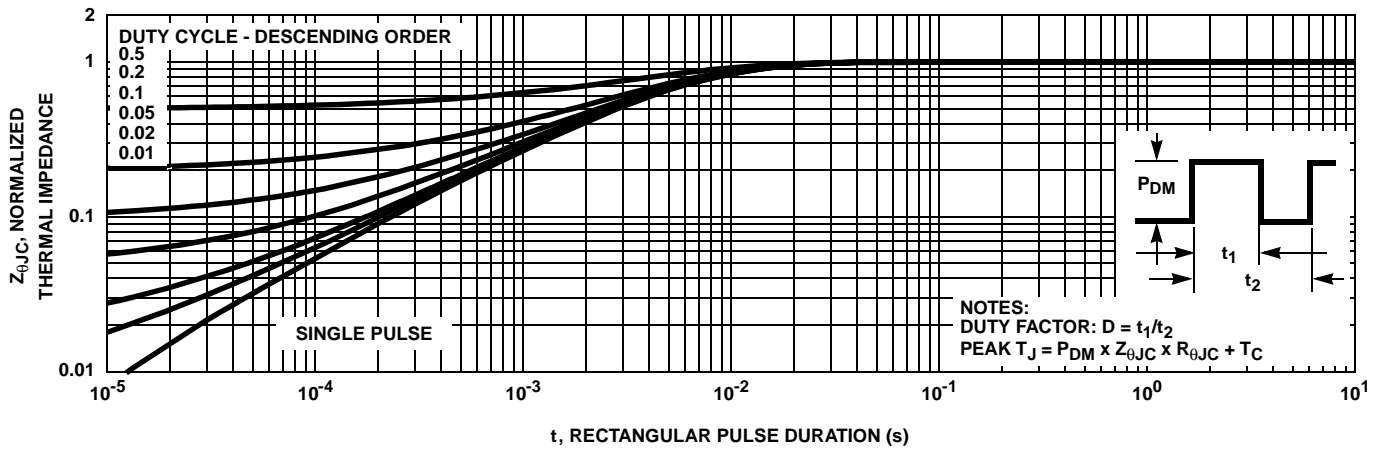


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

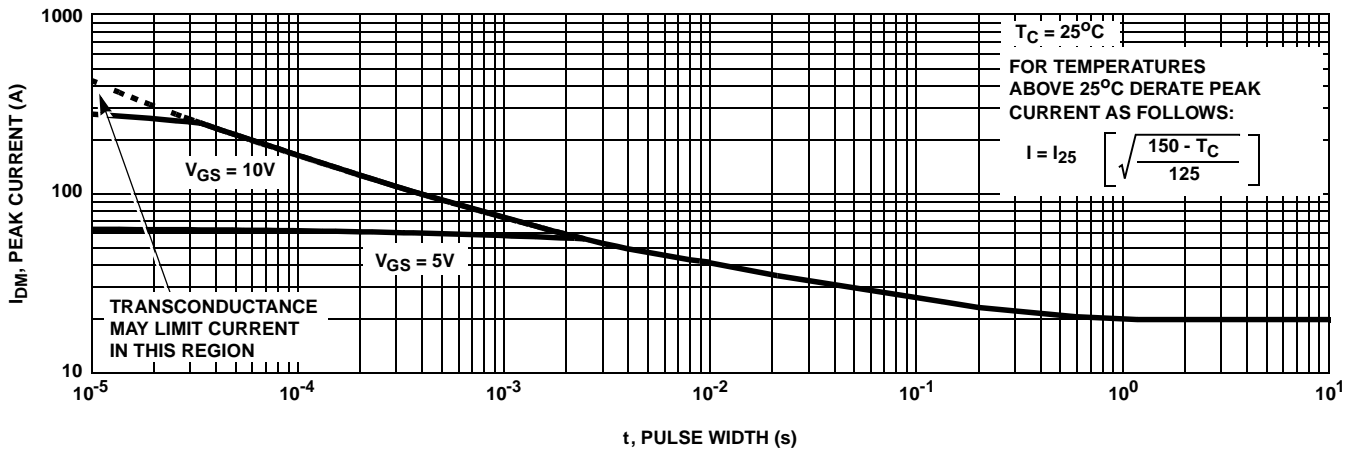


FIGURE 4. PEAK CURRENT CAPABILITY

Typical Performance Curves (Continued)

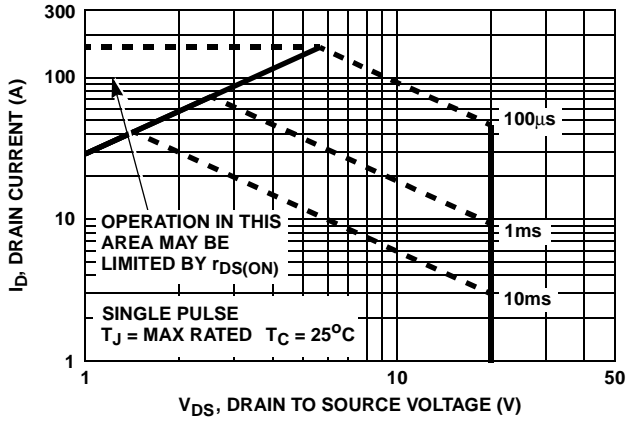


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA

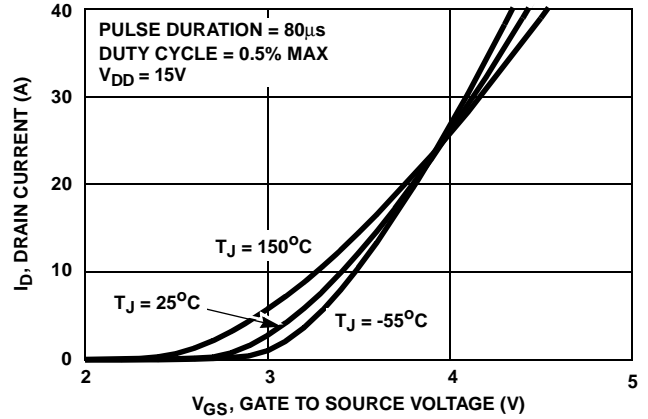


FIGURE 6. TRANSFER CHARACTERISTICS

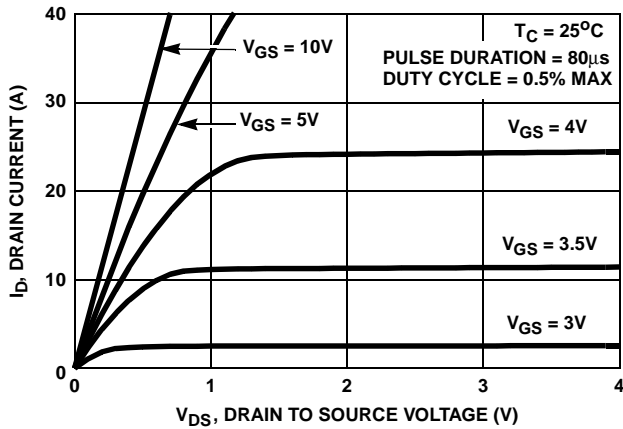


FIGURE 7. SATURATION CHARACTERISTICS

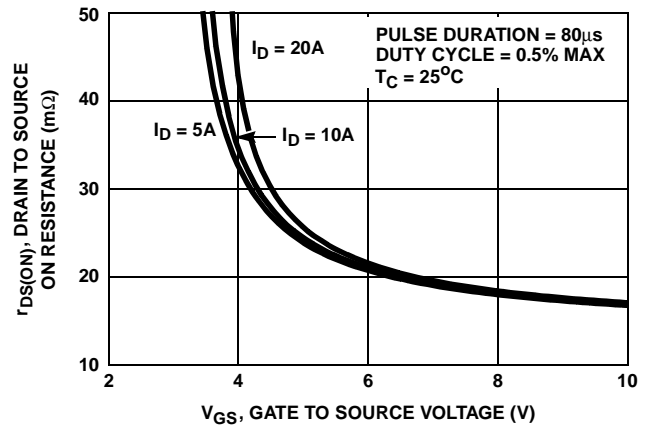


FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

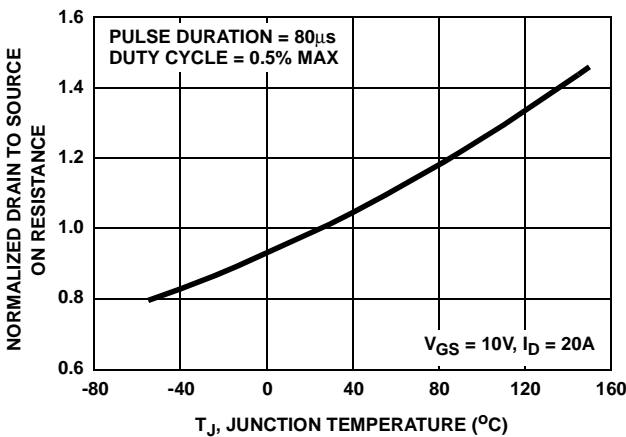


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

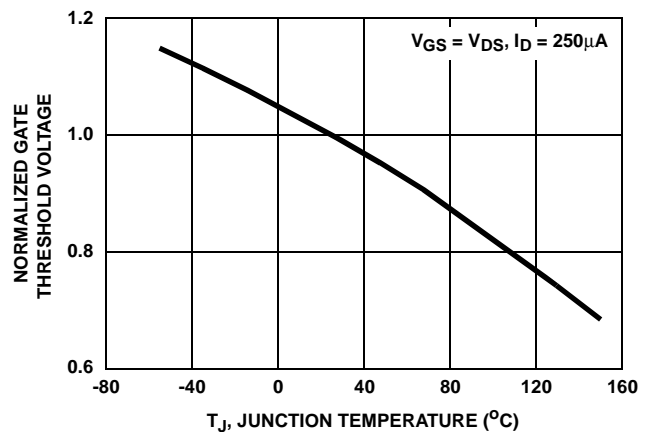


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

Typical Performance Curves (Continued)

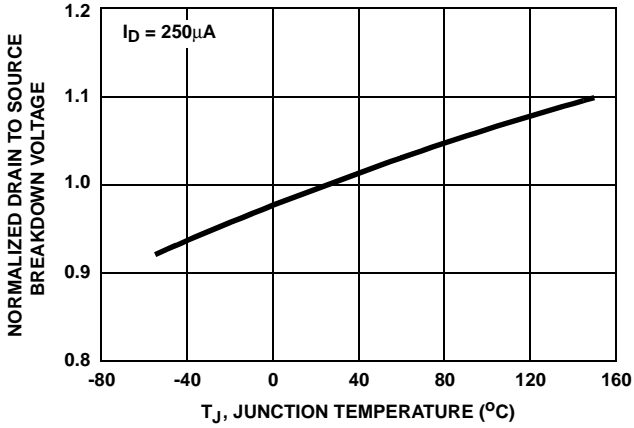


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

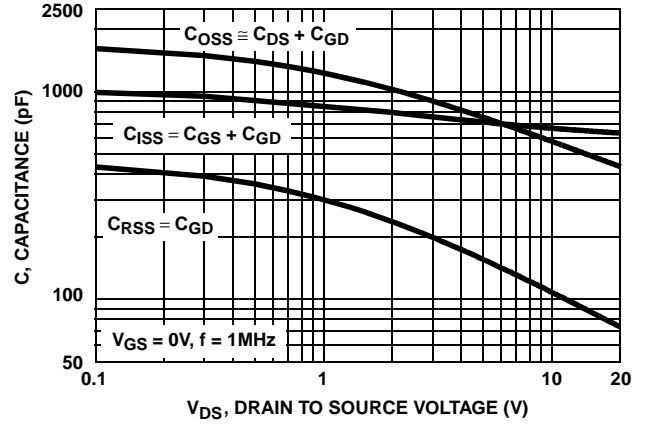
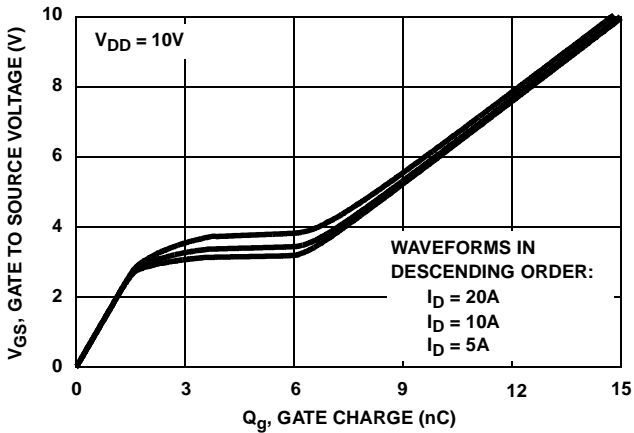


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 13. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

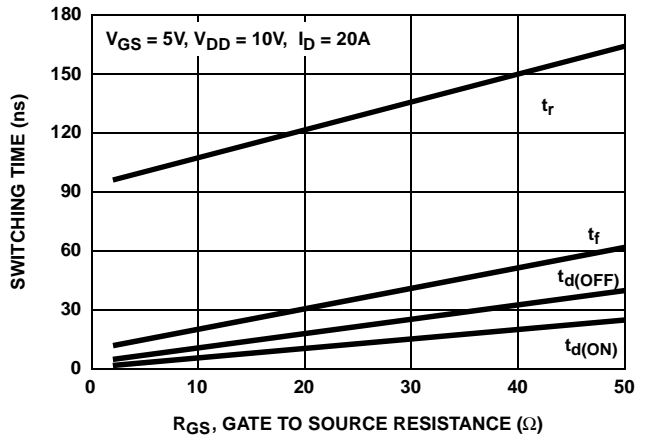


FIGURE 14. SWITCHING TIME vs GATE RESISTANCE

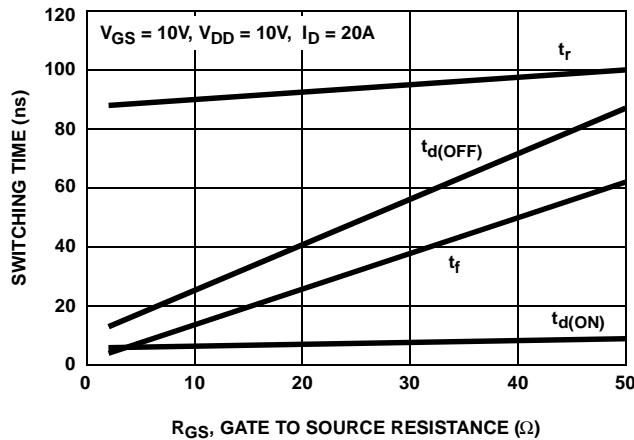


FIGURE 15. SWITCHING TIME vs GATE RESISTANCE

Test Circuits and Waveforms

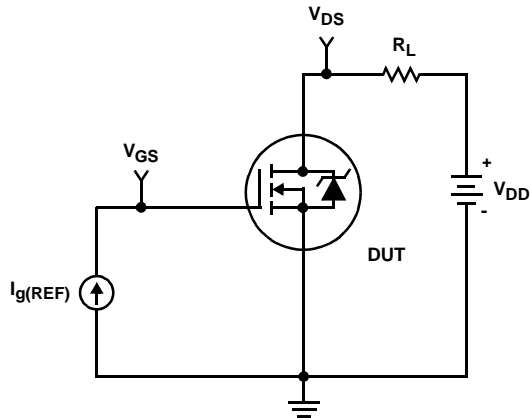


FIGURE 16. GATE CHARGE TEST CIRCUIT

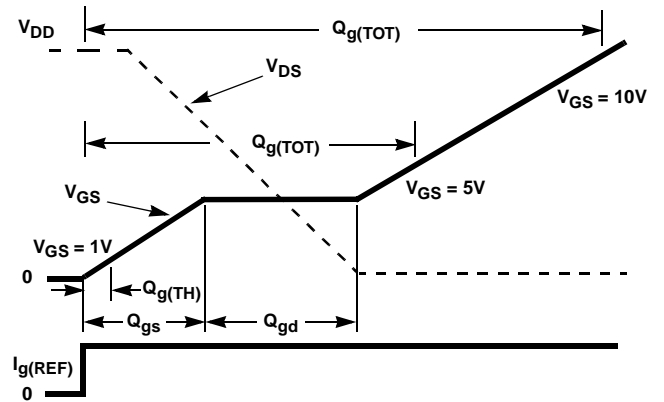


FIGURE 17. GATE CHARGE WAVEFORMS

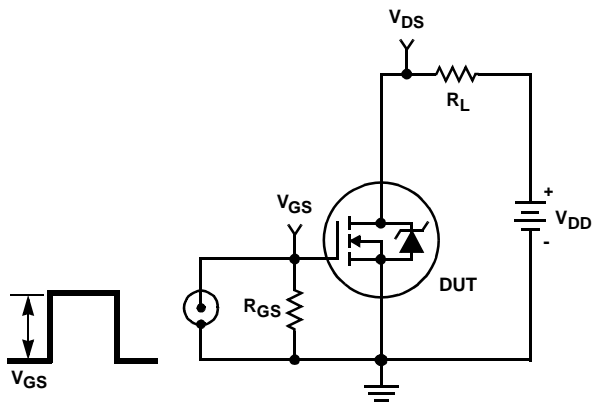


FIGURE 18. SWITCHING TIME TEST CIRCUIT

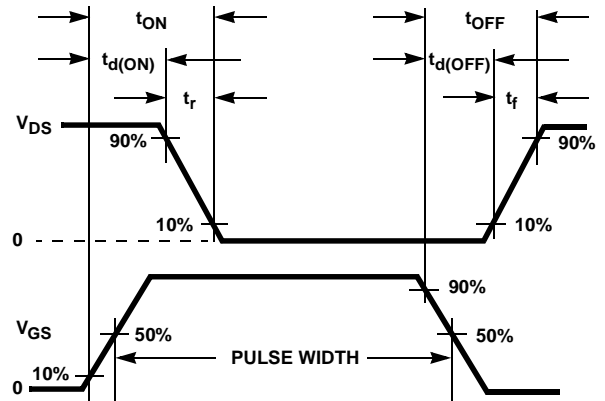


FIGURE 19. SWITCHING TIME WAVEFORM

# HUF76013P3, HUF76013D3S

## PSPICE Electrical Model

.SUBCKT HUF76013P3 2 1 3 ; rev 23March 2000

CA 12 8 6.5e-10  
 CB 15 14 7.0e-10  
 CIN 6 8 5.6e-10

DBODY 7 5 DBODYMOD  
 DBREAK 5 11 DBREAKMOD  
 DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 26  
 EDS 14 8 5 8 1  
 EGS 13 8 6 8 1  
 ESG 6 10 6 8 1  
 EVTHRES 6 21 19 8 1  
 EVTEMP 20 6 18 22 1

IT 8 17 1

LDRAIN 2 5 1.00e-9  
 LGATE 1 9 4.9e-9  
 LSOURCE 3 7 4.9e-9

MMED 16 6 8 8 MMEDMOD  
 MSTRO 16 6 8 8 MSTROMOD  
 MWEAK 16 21 8 8 MWEAKMOD

RBREAK 17 18 RBREAKMOD 1  
 RDRAIN 50 16 RDRAINMOD 1e-3  
 RGATE 9 20 3.0  
 RLDRAIN 2 5 10  
 RLGATE 1 9 49  
 RLSOURCE 3 7 49  
 RSLC1 5 51 RSLCMOD 1e-6  
 RSLC2 5 50 1e3  
 RSOURCE 8 7 RSOURCEMOD 12.5e-3  
 RVTHRES 22 8 RVTHRESMOD 1  
 RVTEMP 18 19 RVTEMPMOD 1

S1A 6 12 13 8 S1AMOD  
 S1B 13 12 13 8 S1BMOD  
 S2A 6 15 14 13 S2AMOD  
 S2B 13 15 14 13 S2BMOD

VBAT 22 19 DC 1

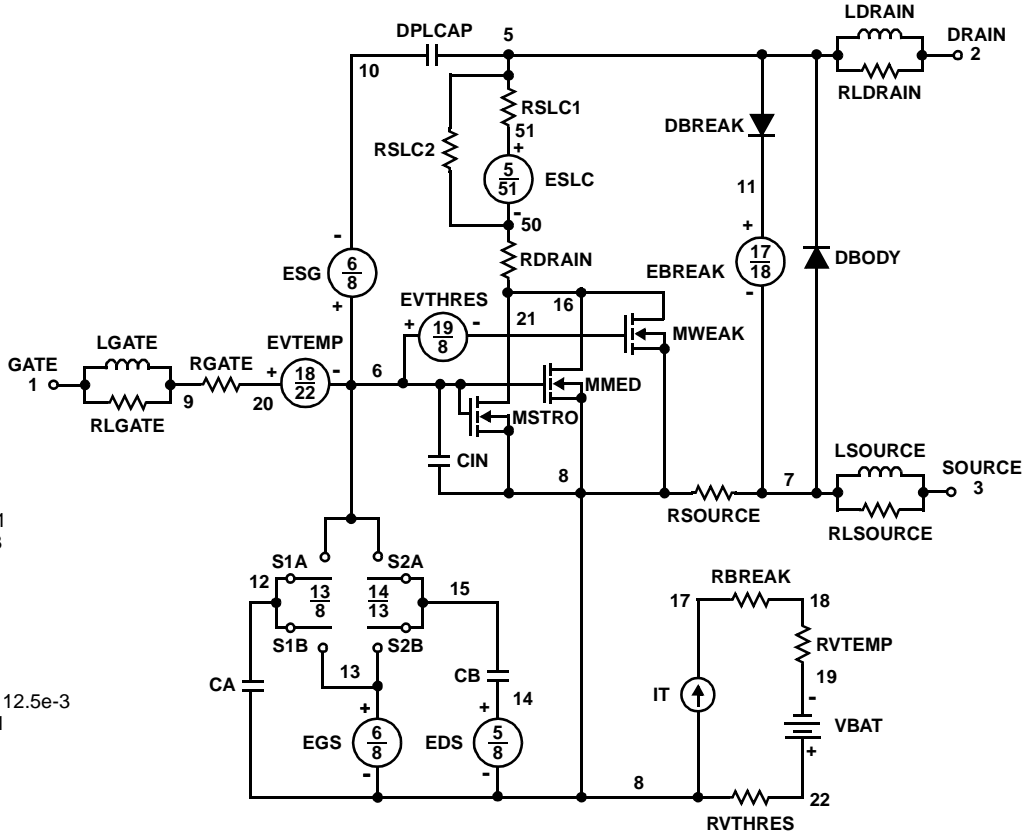
ESLC 51 50 VALUE={(V(5,51)/ABS(V(5,51)))\*(PWR(V(5,51))/(1e-6\*175),2.5))}

.MODEL DBODYMOD D (IS = 5.4e-13 RS = 1.15e-2 TRS1 = 7.0e-5 TRS2 = -1.0e-6 CJO = 12.3e-10 TT = 2.93e-8 M = 0.40)  
 .MODEL DBREAKMOD D (RS = 3.50e-1 TRS1 = 1e-3 TRS2 = -6.5e-6)  
 .MODEL DPLCAPMOD D (CJO = 4.6e-1 OIS = 1e-3 ON = 10 M = 0.6)  
 .MODEL MMEDMOD NMOS (VTO = 2.2 KP = 2.0 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 3.0)  
 .MODEL MSTROMOD NMOS (VTO = 2.66 KP = 40 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u LAMBDA=.01)  
 .MODEL MWEAKMOD NMOS (VTO = 1.90 KP = 0.03 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 30 RS = 0.1)  
 .MODEL RBREAKMOD RES (TC1 = 1.0e-3 TC2 = -1.0e-6)  
 .MODEL RDRAINMOD RES (TC1 = 2.1e-2 TC2 = 6.5e-5)  
 .MODEL RSLCMOD RES (TC1 = 3.5e-3 TC2 = 2e-6)  
 .MODEL RSOURCEMOD RES (TC1 = 1e-3 TC2 = 1e-6)  
 .MODEL RVTHRESMOD RES (TC1 = -1.9e-3 TC2 = -6.0e-6)  
 .MODEL RVTEMPMOD RES (TC1 = -1.8e-3 TC2 = 0)

.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -4.5 VOFF = -1.5)  
 .MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.5 VOFF = -4.5)  
 .MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -0.5 VOFF = 0)  
 .MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 0 VOFF = -0.5)

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.



**SABER Electrical Model**

REV 23March2000

template huf76013p3 n2,n1,n3  
electrical n2,n1,n3

```
{
var i iscl
dp..model dbodymod = (isl = 5.4e-13, rs = 1.15e-2, trs1 = 7.0e-5, trs2 = -1e-6, cjo = 12.3e-10, tt = 2.93e-8, m = 0.40)
dp..model dbreakmod = (rs = 3.50e-1, trs1 = 1e-3, trs2 = -6.5e-6)
dp..model dplcapmod = (cjo = 4.60e-10, isl = 10e-30, nl=10, m = 0.6)
m..model mmedmod = (type=_n, vto = 2.2, kp = 2.0, is = 1e-30, tox = 1)
m..model mstrongmod = (type=_n, vto = 2.66, kp = 40, lamda=0.01, is = 1e-30, tox = 1)
m..model mweakmod = (type=_n, vto = 1.90, kp = 0.03, is = 1e-30, tox = 1, rs=0.1)
sw_vdsp..model s1amod = (ron = 1e-5, roff = 0.1, von = -4.5, voff = -1.5)
sw_vdsp..model s1bmod = (ron = 1e-5, roff = 0.1, von = -1.5, voff = -4.5)
sw_vdsp..model s2amod = (ron = 1e-5, roff = 0.1, von = -0.5, voff = 0)
sw_vdsp..model s2bmod = (ron = 1e-5, roff = 0.1, von = 0, voff = -0.5)
```

```
c.ca n12 n8 = 6.50e-10
c.cb n15 n14 = 7.0e-10
c.cin n6 n8 = 5.60e-10
```

```
dp.dbody n7 n5 = model=dbodymod
dp.dbreak n5 n11 = model=dbreakmod
dp.dplcap n10 n5 = model=dplcapmod
```

```
i.it n8 n17 = 1
```

```
l.l drain n2 n5 = 1.00e-9
l.l gate n1 n9 = 4.9e-9
l.l source n3 n7 = 4.9e-9
```

```
m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u
```

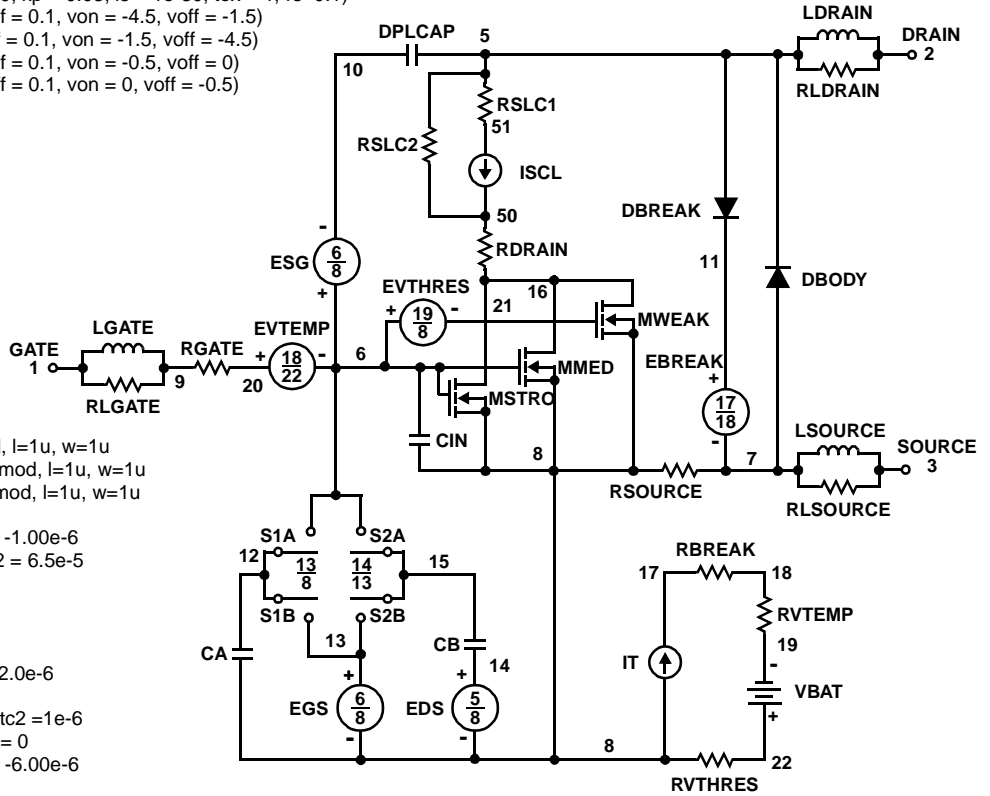
```
res.rbreak n17 n18 = 1, tc1 = 1.0e-3, tc2 = -1.00e-6
res.rdrain n50 n16 = 1e-3, tc1 = 2.1e-2, tc2 = 6.5e-5
res.rgate n9 n20 = 3.0
res.rldrain n2 n5 = 10
res.rlgate n1 n9 = 49
res.rlsource n3 n7 = 49
res.rslc1 n5 n51 = 1e-6, tc1 = 3.5e-3, tc2 = 2.0e-6
res.rslc2 n5 n50 = 1e3
res.rsource n8 n7 = 12.5e-3, tc1 = 1.0e-3, tc2 = 1e-6
res.rvtemp n18 n19 = 1, tc1 = -1.8e-3, tc2 = 0
res.rvthres n22 n8 = 1, tc1 = -1.9e-3, tc2 = -6.00e-6
```

```
spe.ebreak n11 n7 n17 n18 = 26
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1
spe.evthres n6 n21 n19 n8 = 1
```

```
sw_vdsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vdsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vdsp.s2a n6 n15 n14 n13 = model=s2amod
sw_vdsp.s2b n13 n15 n14 n13 = model=s2bmod
```

```
v.vbat n22 n19 = dc=1
```

```
equations {
i (n51->n50) +=iscl
iscl: v(n51,n50) = (((v(n5,n51))/(1e-9+abs(v(n5,n51)))))*((abs(v(n5,n51))*1e6/175)** 2.5))
}
```



### SPICE Thermal Model

REV 23 March 2000

HUF76013T

CTHERM1 th 6 1.0e-3  
 CHERM2 6 5 2.80e-3  
 CHERM3 5 4 3.00e-3  
 CHERM4 4 3 3.40e-3  
 CHERM5 3 2 6.40e-3  
 CHERM6 2 tl 9.50e-2

RHERM1 th 6 1.85e-2  
 RHERM2 6 5 4.61e-2  
 RHERM3 5 4 1.30e-1  
 RHERM4 4 3 7.29e-1  
 RHERM5 3 2 1.10  
 RHERM6 2 tl 1.46e-1

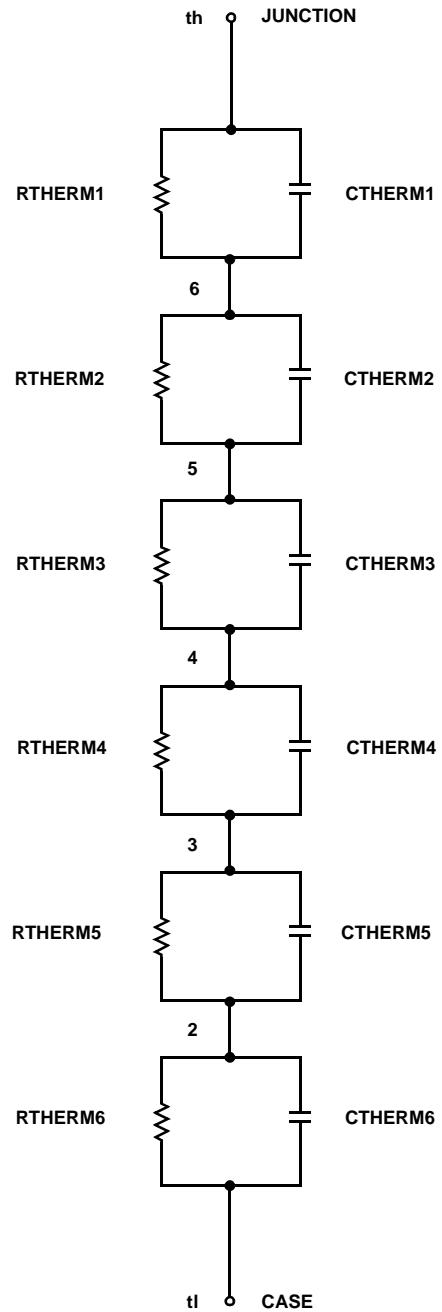
### SABER Thermal Model

SABER thermal model HUF76013T

```

template thermal_model th tl
thermal_c th, tl
{
    ctherm.ctherm1 th 6 = 1.0e-3
    ctherm.ctherm2 6 5 = 2.80e-3
    ctherm.ctherm3 5 4 = 3.00e-3
    ctherm.ctherm4 4 3 = 3.40e-3
    ctherm.ctherm5 3 2 = 6.40e-3
    ctherm.ctherm6 2 tl = 9.50e-2

    rtherm.rtherm1 th 6 = 1.85e-2
    rtherm.rtherm2 6 5 = 4.61e-2
    rtherm.rtherm3 5 4 = 1.30e-1
    rtherm.rtherm4 4 3 = 7.29e-1
    rtherm.rtherm5 3 2 = 1.10
    rtherm.rtherm6 2 tl = 1.46e-1
}
    
```



## TRADEMARKS

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